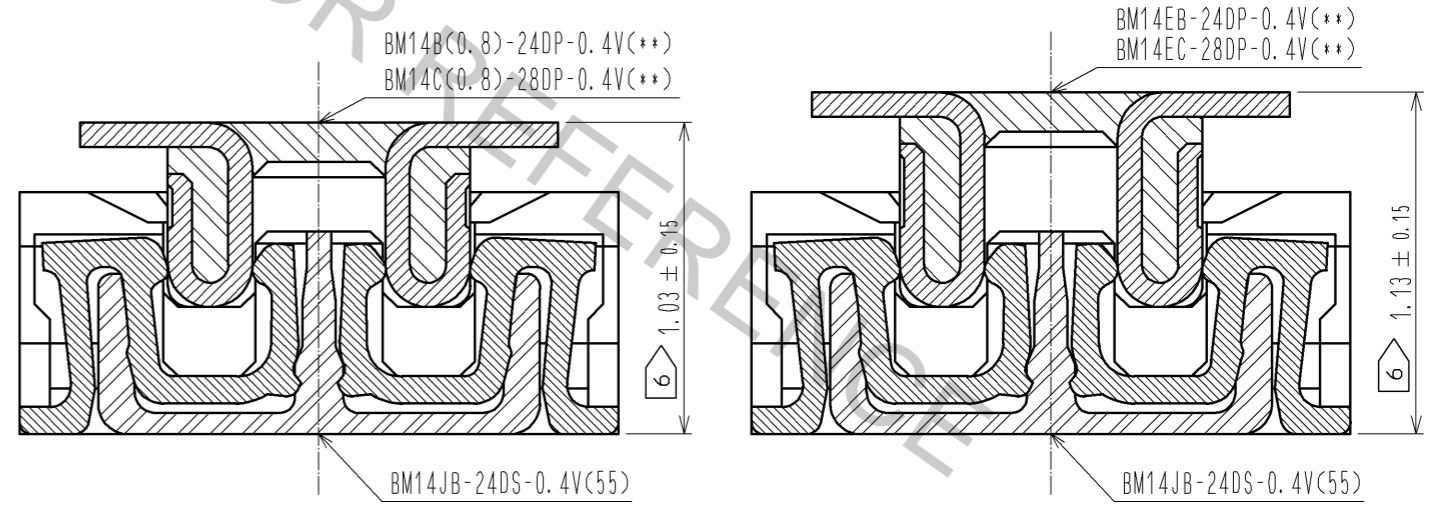


ENGAGEMENT FIGURE (FREE)

ENGAGEMENT FIGURE (FREE)



- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
 2 CONTACT PLATING SPECIFICATIONS.
 CONTACT AREA : GOLD 0.05 μm MIN
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
 3 EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
 4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
 5 GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.
 6 THE DIMENSIONS INDICATED IN THE FIGURE IS REFERENCE.
 AN ELECTRIC PERFORMANCE IS GUARANTEED BY BEING MAINTAINED AS SHOWN IN THE FIGURE.

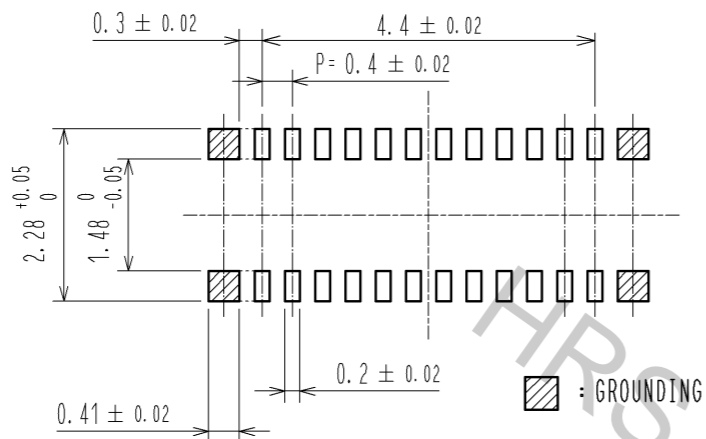
SPECIMEN	
BM14B(0.8)-24DP-0.4V(**)	BM14C(0.8)-28DP-0.4V(**)
BM14EB-24DP-0.4V(**)	BM14EC-28DP-0.4V(**)

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PS		CLEAR(ENBOSSED CARRIER TAPE)	6	PS		CLEAR(REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2		5	PS		BLACK(PLASTIC REEL)
1	LCP		UL94 V-0, BLACK	4	POLYESTER		CLEAR(COVER TAPE)

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	△	APPROVED : KH. IKEDA 11.07.04			
			CHECKED : AR. TAKAHASHI 11.07.04			
			DESIGNED : SH. HOSODA 11.07.04			
			DRAWN : YN. SAKAMOTO 11.07.04			

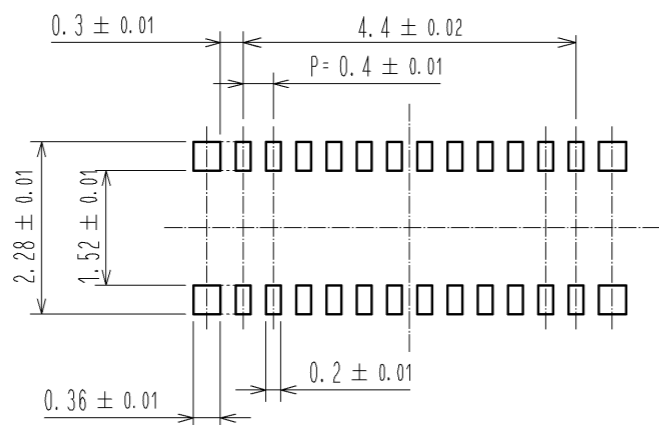
DRAWING NO.	EDC3-331561-01
PART NO.	BM14JB-24DS-0.4V(55)
CODE NO.	CL684-8227-2-55

◆ RECOMMENDED PCB LAYOUT

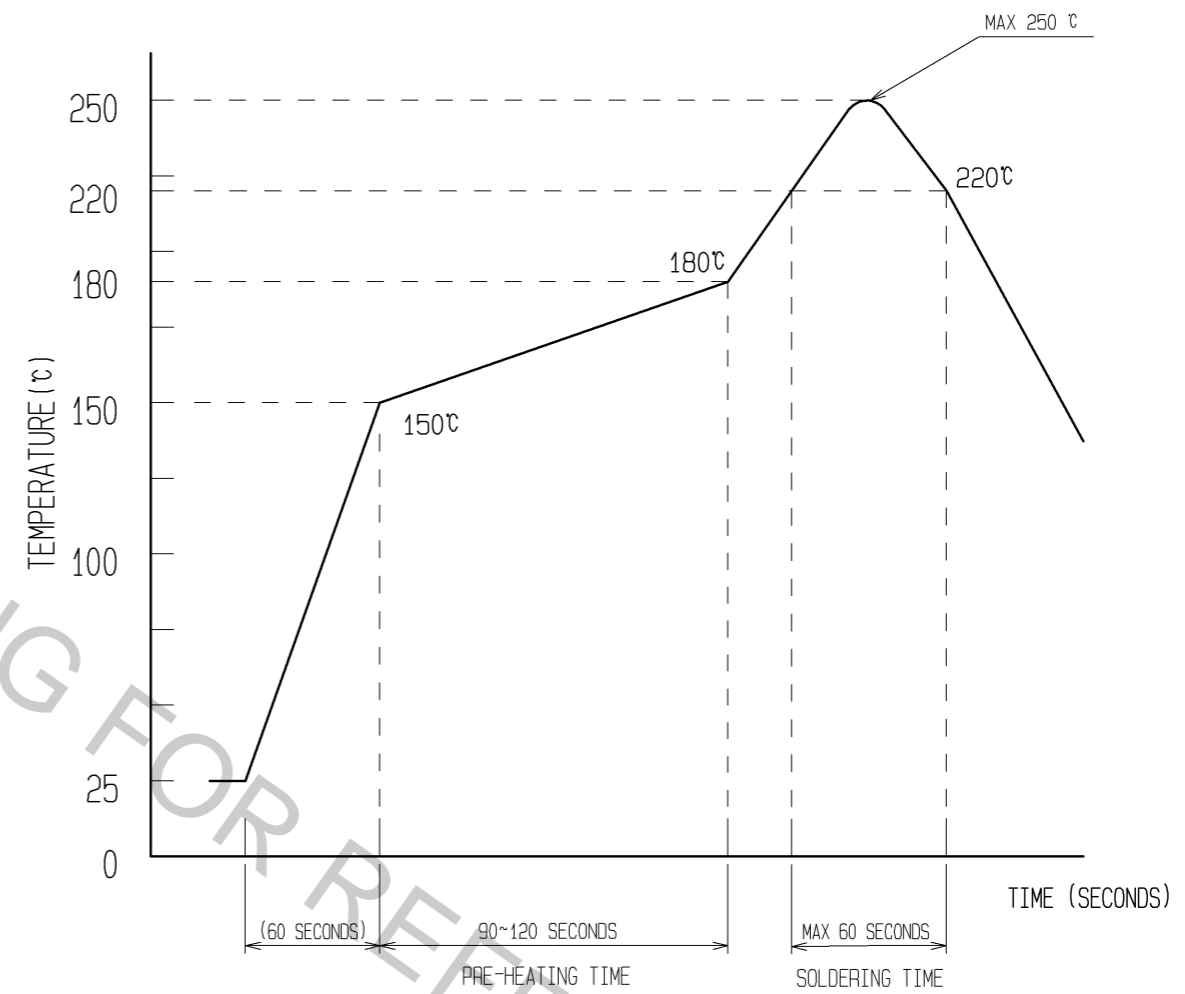


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



7 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

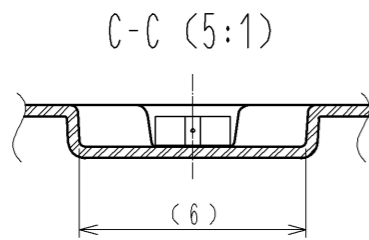
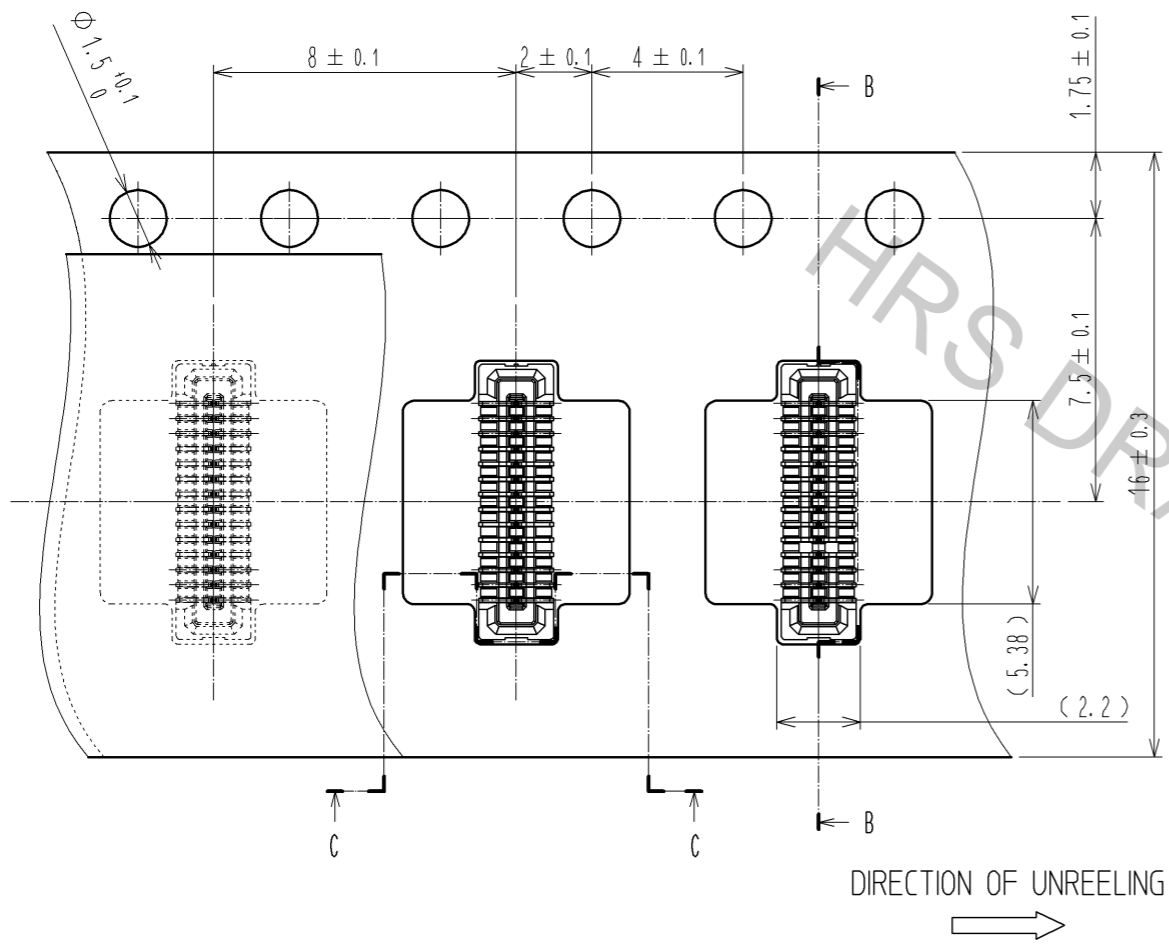


- REFLOW METHOD: IR REFLOW.
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC. MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 - PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 sec.

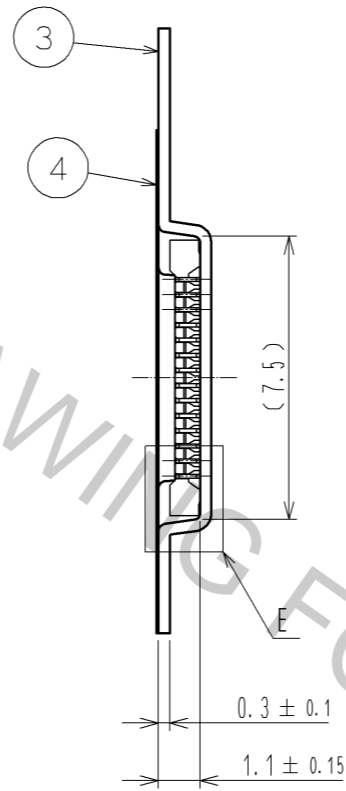
7 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC3-331561-01
	PART NO.	BM14JB-24DS-0.4V(55)
	CODE NO.	CL684-8227-2-55
		△ 2/3

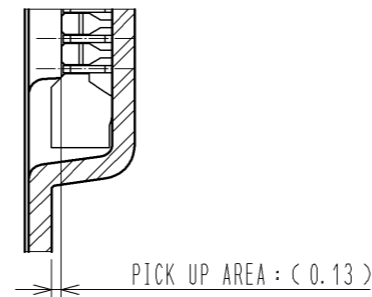
EMBOSED CARRIER TAPE PACKAGING (5:1)



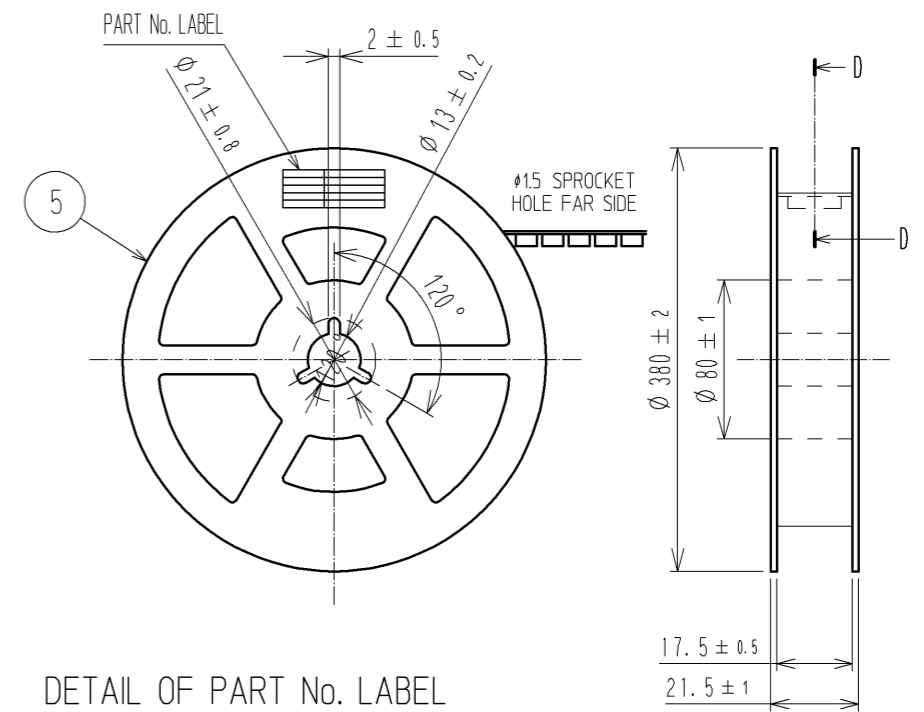
B-B (5:1)



E (10:1)



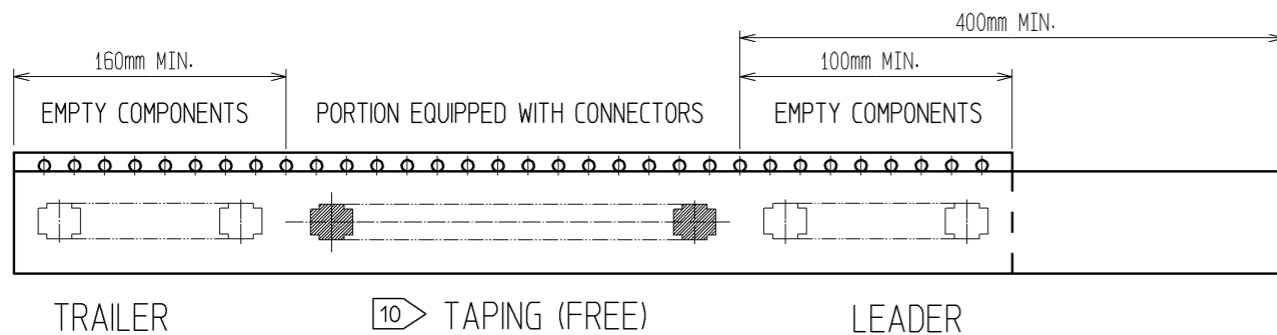
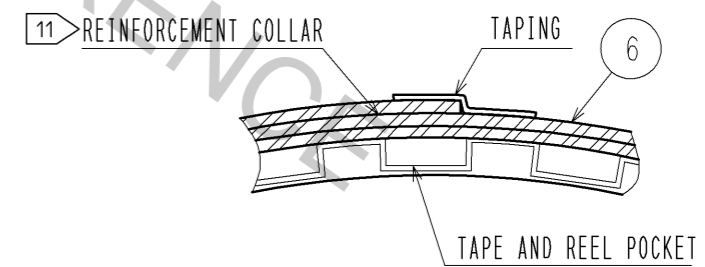
STYLE AND DIMENTION OF REEL (FREE)



DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	
製造年月日	** ** *
製品コード	CL0684-8227-2-55
製品名	BM14JB-24DS-0.4V(55)
数量	500
納入者	ヒロセ電機(株)

D-D (FREE)



- 8. PER REEL 8000 CONNECTORS.
- 9. THE DIMENSIONS IN PARENTHESSES ARE FOR REFERENCE.
- 10 REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 11 AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

HRS	DRAWING NO.	EDC3-331561-01
	PART NO.	BM14JB-24DS-0.4V(55)
	CODE NO.	CL684-8227-2-55
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